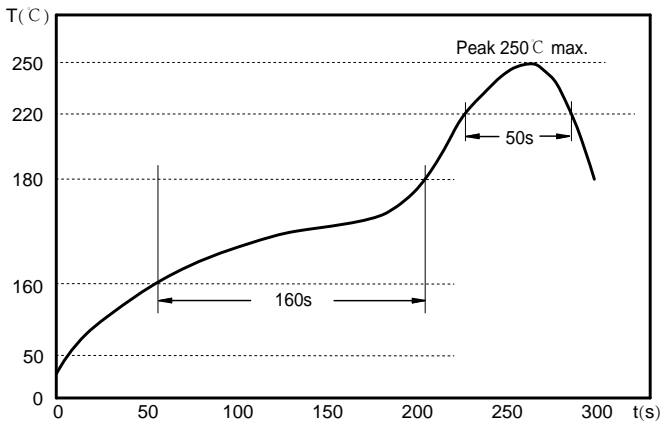


Soldering Reflow:



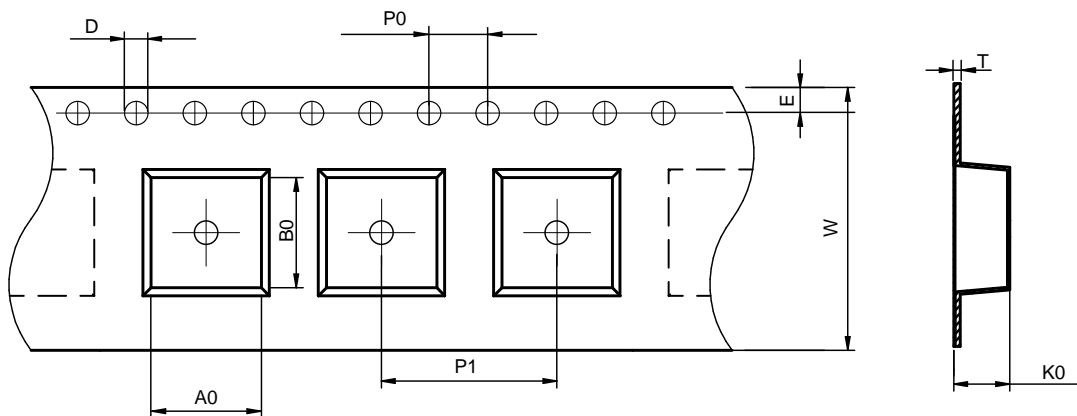
Preheat condition: 160 ~180°C / 160 sec.

Allowed time above 220°C : 50 sec.

Max temperature: 250°C.

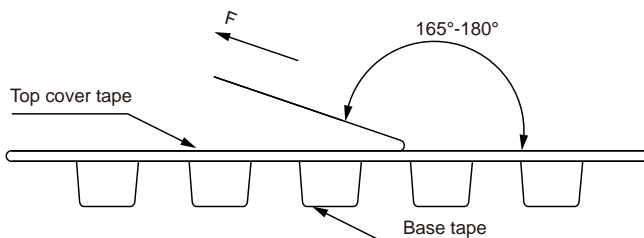
Packaging Information:

Tape Dimension :



Series	A0	B0	D	P0	P1	W	K0	E	T
NRSE8040	9.40±0.1	9.40±0.1	1.50±0.1	4.00±0.1	12.00±0.1	16.00±0.3	4.40±0.1	1.75±0.1	0.40±0.05

Peel force of top cover tape:

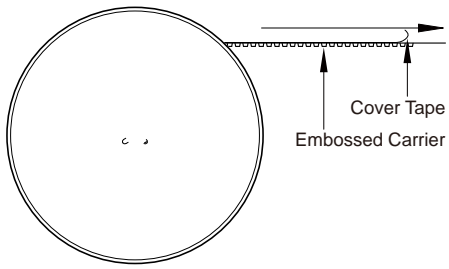


The peel force of top cover tape shall be between 0.03 to 0.98 N

Product Marking:

Marking	Printing (Inductance)
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Reel Dimension: [mm]



Packaging Quantity: